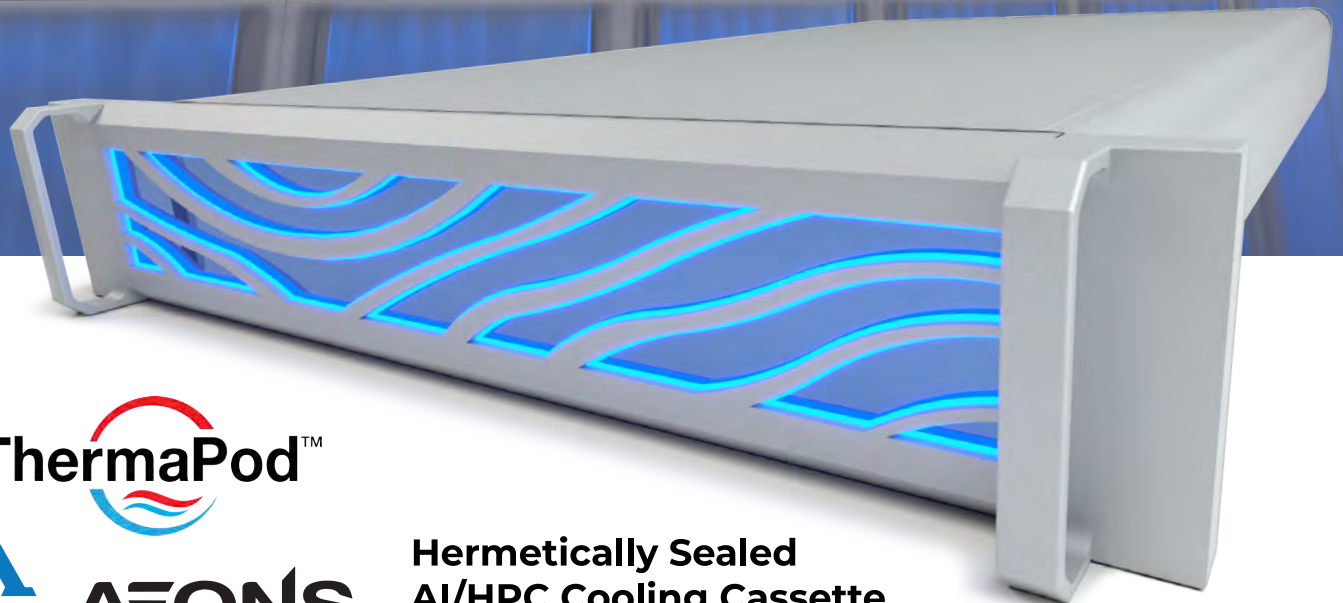


# THE BEST WAY TO BE COOL

The ThermaPod™  
Cooling Cassette



ThermaPod™



Hermetically Sealed  
AI/HPC Cooling Cassette  
Versatile, Scalable, and Future-Proof.

# ThermaPod™ – Adaptable AI/HPC Cooling

## System Purpose

A hermetically sealed cooling cassette that is capable of operating in multiple cooling modes. ThermaPod design target:

**15–25 kW per 2U** (mode-dependent)

Designed for Facility-to-Chip™ integration, supporting single-phase and two-phase cooling. Configurable for immersion, spray, or direct-to-chip thermal transfer.

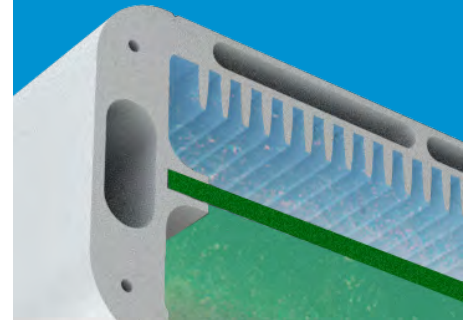
## Modes & Panel Role

- 1. Two-Phase Immersion –**  
Roof = primary condenser; other panels assist.
- 2. Two-Phase Spray**  
Roof = primary condenser; other panels assist.
- 3. Direct-to-Chip (Indirect)**  
Roof = micro AC; other panels manage liquid cooling.



## Key Differentiator

All structural panels act as heat exchangers with mode-dependent roles.



Anodized Aluminum body is hermetically sealed.

AI/HPC circuitry may be cooled using conventional cold plates.

AI/HPC circuitry is captured inside a cool chamber.

Endcaps control fluid direction, input, and output.

All structural panels are engineered with internal channels for heat transfer throughout the ThermaPod™ Cooling Cassette.



All Graphic content created by  
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